

Title (en)

METHOD AND APPARATUS FOR PLASMA DICING A SEMI-CONDUCTOR WAFER

Title (de)

VERFAHREN UND VORRICHTUNG FÜR PLASMA-SCHNEIDEN EINES HALBLEITERWAFERS

Title (fr)

PROCÉDÉ ET APPAREIL DE DÉCOUPAGE DE PUCE PAR PLASMA D'UNE TRANCHE DE SEMI-CONDUCTEUR

Publication

**EP 2965349 A2 20160113 (EN)**

Application

**EP 14712447 A 20140303**

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Abstract (en)

[origin: WO2014137905A2] The present invention provides a method for plasma dicing a substrate. The method comprising providing a process chamber having a wall; providing a plasma source adjacent to the wall of the process chamber; providing a work piece support within the process chamber; placing the substrate onto a support film on a frame to form a work piece work piece; loading the work piece onto the work piece support; providing a clamping electrode for electrostatically clamping the work piece to the work piece support; providing a mechanical partition between the plasma source and the work piece; generating a plasma through the plasma source; and etching the work piece through the generated plasma.

IPC 8 full level

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CPC (source: EP)

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Citation (search report)

See references of WO 2014137905A2

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